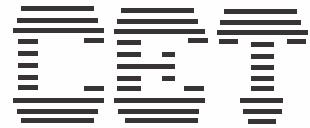


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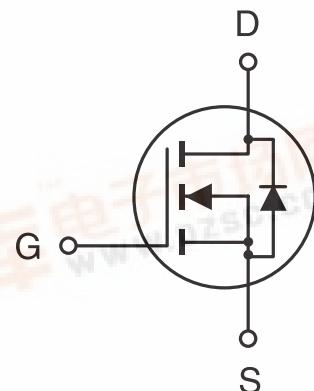


## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

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- 60V , 15A ,  $R_{DS(ON)}=80m\Omega$  @  $V_{GS}=10V$ .  
 $R_{DS(ON)}=85m\Omega$  @  $V_{GS}=5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability.
- TO-252 package.



### ABSOLUTE MAXIMUM RATINGS ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 16$	V
Drain Current-Continuous -Pulsed	$I_D$	15	A
	$I_{DM}$	45	A
Drain-Source Diode Forward Current	$I_S$	15	A
Maximum Power Dissipation @ $T_c=25^\circ C$ Derate above 25°C	$P_D$	50	W
		0.3	W/ $^\circ C$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	$^\circ C$

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ C/W$

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## ELECTRICAL CHARACTERISTICS (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V			25	μA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±16V, V <sub>DS</sub> = 0V			±100	nA
<b>ON CHARACTERISTICS<sup>a</sup></b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	2	V
Drain-Source On-State Resistance	R <sub>D(S)ON</sub>	V <sub>GS</sub> = 5V, I <sub>D</sub> = 6A			85	mΩ
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 12A			80	mΩ
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> = 5V, V <sub>GS</sub> = 10V	15			A
Forward Transconductance	g <sub>F</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 6A		8		S
<b>DYNAMIC CHARACTERISTICS<sup>b</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V f = 1.0MHz		430	600	pF
Output Capacitance	C <sub>oss</sub>			126	200	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			28	100	pF
<b>SWITCHING CHARACTERISTICS<sup>b</sup></b>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> = 30V, I <sub>D</sub> = 15A, V <sub>GEN</sub> = 5V, R <sub>GEN</sub> = 51Ω,		15	20	ns
Rise Time	t <sub>r</sub>			210	250	ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			55	100	ns
Fall time	t <sub>f</sub>			80	150	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 48V, I <sub>D</sub> = 15A, V <sub>GS</sub> = 5V		14	17	nC
Gate-Source Charge	Q <sub>gs</sub>			1		nC
Gate-Drain Charge	Q <sub>gd</sub>			2		nC

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## ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}$ , $I_S = 6\text{A}$		0.95	1.3	V

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### Notes

- a. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.

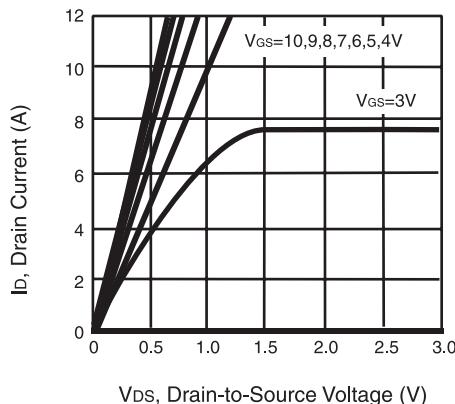


Figure 1. Output Characteristics

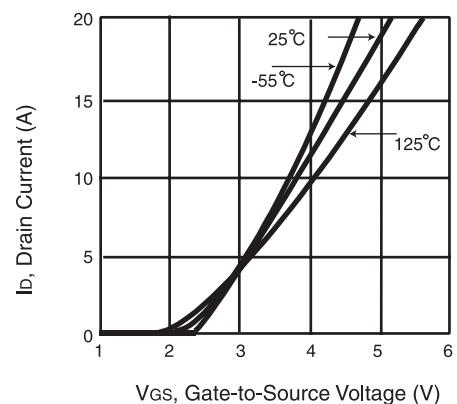


Figure 2. Transfer Characteristics

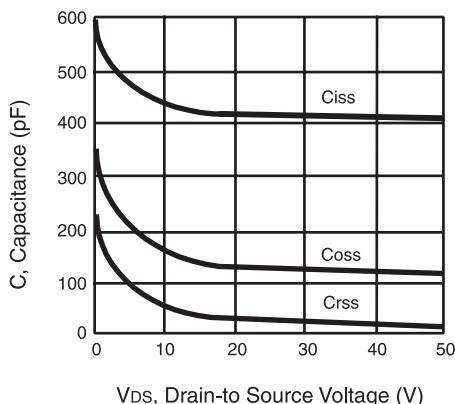


Figure 3. Capacitance

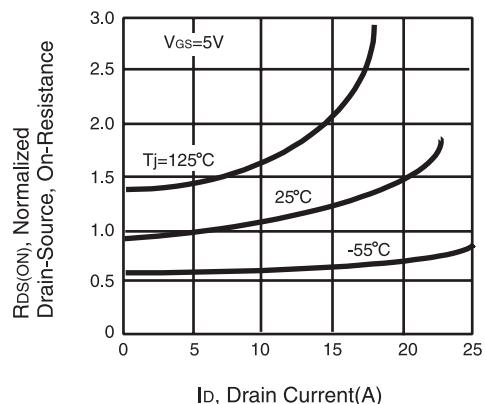
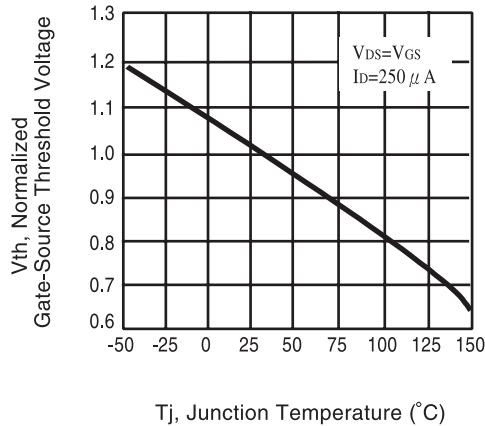


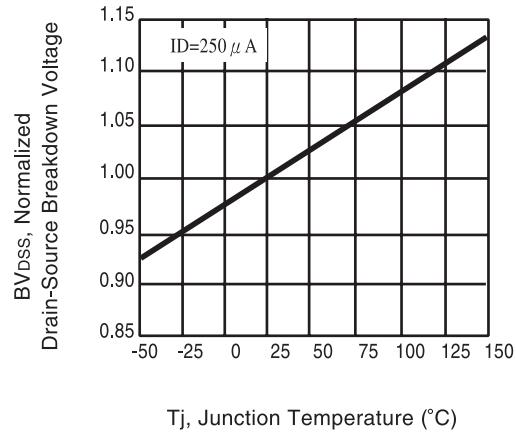
Figure 4. On-Resistance Variation with Drain Current and Temperature

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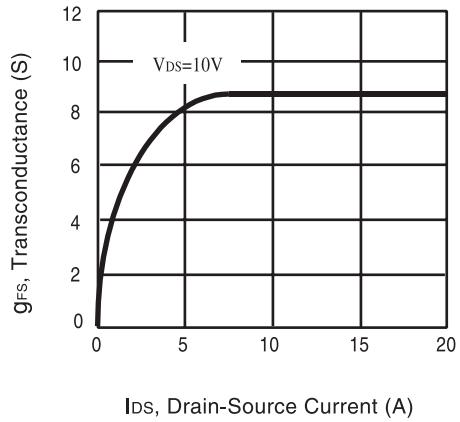
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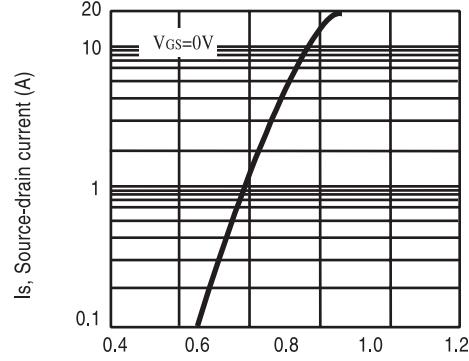
**Figure 5. Gate Threshold Variation with Temperature**



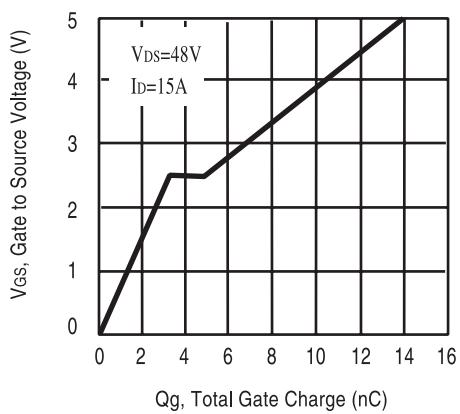
**Figure 6. Breakdown Voltage Variation with Temperature**



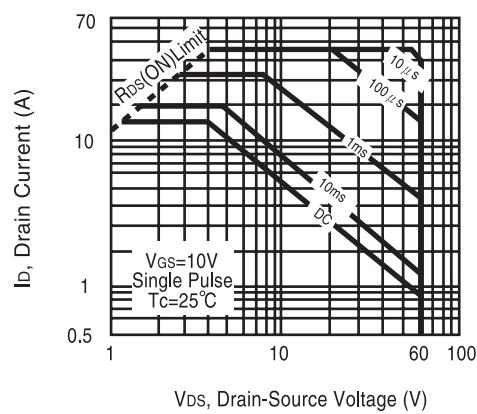
**Figure 7. Transconductance Variation with Drain Current**



**Figure 8. Body Diode Forward Voltage Variation with Source Current**



**Figure 9. Gate Charge**



**Figure 10. Maximum Safe Operating Area**

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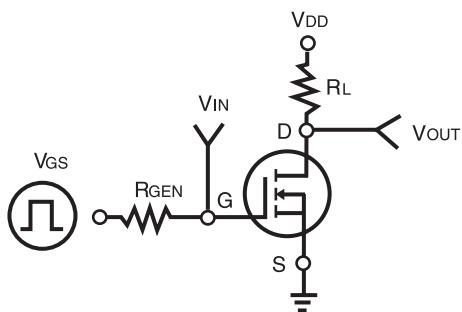


Figure 11. Switching Test Circuit

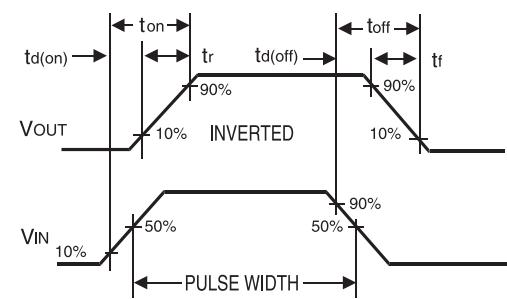


Figure 12. Switching Waveforms

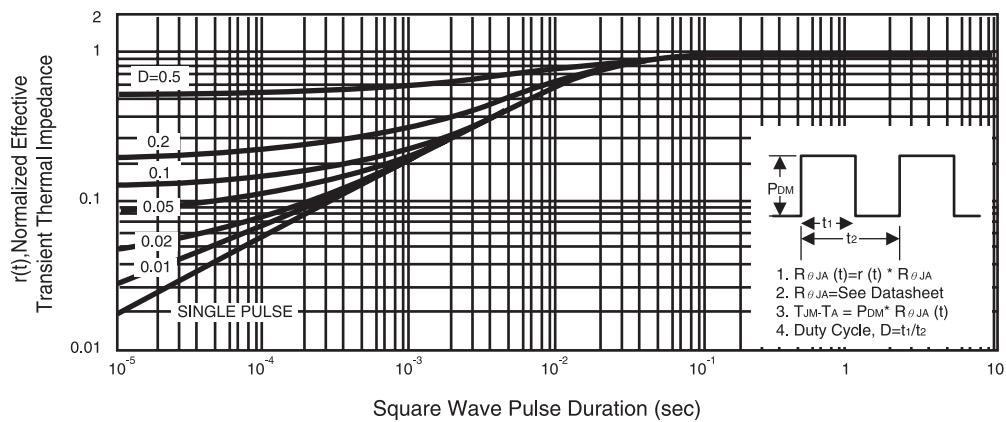


Figure 13. Normalized Thermal Transient Impedance Curve